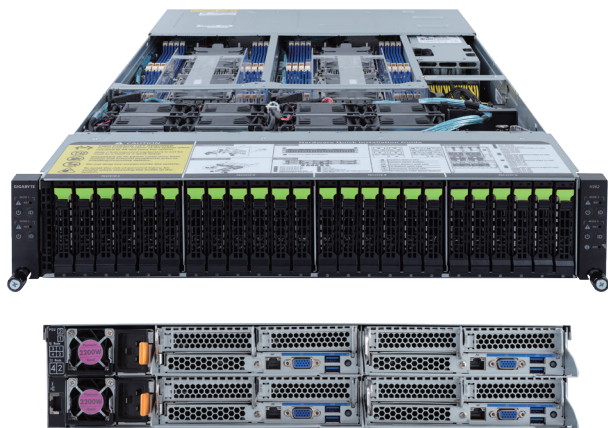


H262-N01

High Density Server - DP 2U 4-Node



Features

- 2U - 4 nodes with rear access to the node trays
- 3rd Gen. Intel® Xeon® Scalable Processors
- 8-Channel RDIMM/LRDIMM DDR4, 64 x DIMMs
- Supports Intel® Optane™ Persistent Memory 200 series
- Dual ROM Architecture supported
- Intel® C621A Express Chipset
- 4 x Dedicated management ports
- 1 x CMC global management port
- 24 x 2.5" SATA/SAS/Gen4 NVMe hot-swap HDD/SSD bays
- 8 x Low profile PCIe Gen4 x16 expansion slots
- 4 x OCP 3.0 Gen4 x16 mezzanine slots
- 2200W 80 PLUS Platinum redundant PSU

Specification

Dimensions	2U 4 Nodes - Rear access (W440 x H87.5 x D840 mm)	Front I/O	-
Motherboard	MH62-HD2	Rear I/O	Total: 8 x USB 3.0, 4 x VGA, 4 x MLAN, 1 x CMC LAN
CPU	3rd Gen Intel® Xeon® Scalable Processors Intel® Xeon® Platinum Processor, Intel® Xeon® Gold Processor, Intel® Xeon® Silver Processor 10nm technology, CPU TDP up to 270W Total: 8 x LGA 4189 sockets (Socket P+)	Backplane I/O	Front side_CBP700: 24 x SATA/SAS/Gen4 NVMe ports
Chipset	Intel® C621A Express Chipset	TPM	1 x TPM header with SPI interface Optional TPM2.0 kit: CTM010
Memory	8-Channel DDR4 memory, total 64 x DIMM slots RDIMM/LRDIMM modules up to 128GB supported 3DS RDIMM/LRDIMM modules up to 256GB supported 1.2V modules: 3200/2933/2666 MHz	Power Supply	2 x 2200W redundant PSUs (AC Input: 100-240V)
LAN	4 x Dedicated management ports 1 x 10/100/1000 CMC global management port	System Management	Aspeed® AST2600 management controller GIGABYTE Management Console (AMI MegaRAC SP-X)
Video	Integrated in Aspeed® AST2600 2D Video Graphic Adapter with PCIe bus interface 1920x1200@60Hz 32bpp, DDR4 SDRAM	OS Compatibility	Windows Server 2016 / 2019 RHEL 7.9 (x64) / 8.2 (x64) / 8.3 (x64) SLES 12 SP5 (x64) / 15 SP2 (x64) or later Ubuntu 20.04 LTS (x64) / 20.04.1 LTS (x64) or later VMware ESXi 6.7 Update3 P03 / 7.0 Update2 Citrix Hypervisor 8.2.0
Storage	24 x 2.5" SATA/SAS/NVMe hot-swappable HDD/SSD bays	System Fans	8 x 80x80x38mm (16,300rpm)
RAID	ntel® SATA RAID 0/1/5/10	Operating Properties	Operating temperature: 10°C to 35°C Operating humidity: 8-80% (non-condensing) Non-operating temperature: -40°C to 60°C Non-operating humidity: 20%-95% (non-condensing)
Expansion Slots	Total: 8 x low-profile PCIe x16 slots (Gen4 x16) 4 x OCP 3.0 mezzanine slots (Gen4 x16)	Packaging Content	1 x H262-N01, 8 x CPU heatsinks, 1 x Rail kit
Internal I/O	Per node: 1 x COM header, 1 x TPM header, 1 x VROC connector, 1 x BMC SGPIO header, 1 x JTAG BMC header, 1 x PLD header, 1 x Clear CMOS jumper, 1 x IPMB connector	Reference Numbers	Barebone package: 6NH262NO1MR-00 - Motherboard: 9MH62HD2NR-00 - VROC module: 25FD0-R181N0-10R (option) - Rail kit: 25HB2-A66122-K0R - CPU heatsink: 25ST1-44320S-M1R / 25ST1-44320T-M1R - Power Supply: 25EP0-222003-D0S



Learn more about GIGABYTE server solutions, visit www.gigabyte.com/Enterprise

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